

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	300533	method and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:28
S2	90151	S1 and (arpeture or cavity or hole or opening or holo)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 16:26
S3	2698	S2 and (bonding adj pad) and (optic\$5 or light or led)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 14:57
S4	15405	S2 and pad and (optic\$5 or light or led)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 16:27
S5	2141	S4 and "438".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:03
S6	1376	S5	USPAT	OR	ON	2005/08/08 15:04
S7	1376	S5	USPAT	OR	ON	2005/08/08 15:04
S8	488	S6 and @pd<"20000901"	USPAT	OR	ON	2005/08/08 16:28
S9	1	("5357056").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/08 15:23
S10	1	("6713876").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/08 15:24
S11	1	("6798031").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/08 15:26
S12	1	("6786588").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/08 15:26
S13	0	("6786588b1").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/08 15:27
S14	23223	"257".clas. and package	USPAT	OR	ON	2005/08/08 16:25
S15	7586	"438".clas. and package	USPAT	OR	ON	2005/08/08 16:25
S16	102147	S1 and (aperture or cavity or hole or opening or holo)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 16:26

S17	16644	S16 and pad and (optics or led)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 16:27
S18	5052	S17 and @pd<"20000901"	USPAT	OR	ON	2005/08/08 16:38
S19	505	S18 and shell	USPAT	OR	ON	2005/08/08 16:43
S20	500	(438/116,64).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/12 12:12
S21	500	(438/116,64).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/09 09:02
S22	1	("20030056967").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 10:44
S23	1	("20030197285").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 10:44
S24	4632	(method or forming) and solder and glass and optical and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 11:16
S25	9496	S24 leadless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 11:17
S26	6397	S25 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 11:16
S27	182	S24 and leadless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 11:17
S28	10	((("5357056") or ("5477081") or ("5675474") or ("5702985") or ("5865935") or ("5867368") or ("6147389") or ("6351027") or ("20020043706") or ("6384473"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:06
S29	3	((("6531341") or ("20020089044") or ("20030056967") or ("20030197285"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:08
S30	2	((("5687474") or ("6649991") or ("6713876"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:09

S31	0	((("653134I") or ("67I3876"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:09
S32	0	((("653134I") or ("67I3876"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/09 13:14
S33	0	("67I3876").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/09 13:13
S34	0	("67I3876").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/09 13:13
S36	0	653134I.pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:14
S37	1	("653134I").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:19
S38	3	((("4404648") or ("20040212055") or ("20040217454"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:21
S39	0	("64404648").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/09 13:21
S40	0	"64404648".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:21
S41	2	"6404648".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 13:20
S42	545925	package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:28
S43	7994884	method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:29

S44	4790277	aperture or opening or hole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:30
S45	1699032	cavity or hollow or depression	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:31
S46	301225	S42 and S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:32
S47	871325	S44 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:33
S48	41542	S46 and S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:34
S49	787063	transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:34
S50	14160	encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:34
S51	2251	S49 and S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:34
S52	218	S49 adj S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:34
S53	54	S48 and S52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 09:48

S54	365	S48 and S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 11:17
S55	484	(257/680).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/11 12:05
S56	73678	image adj sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:05
S57	3763	S42 and S56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:05
S58	2895	S43 and S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:06
S59	2895	S58 and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:07
S60	13729	"1" and S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:07
S61	143	S59 and S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:07
S62	833	(257/707).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/11 16:17
S63	495	S62 and method and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 16:18
S64	1	("20040212055").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/12 09:02
S65	57	depositing and (transparent adj encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 09:06

S66	124	deposit\$3 and (transparent adj encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:23
S67	253	(257/729).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/12 11:24
S68	26	S67 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:25
S69	500	(438/116,64).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/12 12:12
S70	10	S69 and (transparent adj encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/12 12:13
S71	0	transparent adj encapslant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 10:22
S72	788382	transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 10:22
S73	14162	encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 10:22
S74	2252	S72 and S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 10:22
S75	41	S74 and (solder adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 11:04
S76	787	(257/431).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:04
S77	889	(257/432).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:05
S78	633	(257/433).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:05

S79	296	(257/434).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:05
S80	1473	(257/676).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:05
S81	0	("I34andI35andI36andI37andI38"). PN.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:06
S82	0	S76 and S77 and S78 and S79 and S80	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 11:06
S83	0	257/431,432,433,434,676	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 11:07
S84	3641	(257/431,432,433,434,676).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 11:08
S85	491	S84 and optic\$2 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 13:14
S86	1764	S84 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 13:15
S87	55	S86 and (solder adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 13:23
S88	441	S84 and solder and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 13:29
S89	296	(257/434).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/15 16:32
S90	4391	((257/431,432,433,434,676,680) or (438/116,64)).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/08/17 11:37
S91	166	S90 and encapsul\$3 and (fill or overfill) and (window or aperture or opening or recess or groove or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 11:38

S92	42	backing adj cap	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 13:40
S93	1	("6870238").PN.	US-PGPUB; USPAT	OR	OFF	2005/08/18 13:43
S94	19	exposito-juan.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 13:47
S95	61	exposito.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 13:47
S96	2	"6713876".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 14:29